

PCN Supporting Data Package

PCN#: 20260611001.1

Title: Qualification of TIEM as an additional Assembly site for select devices

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Site Information

TI-CDAT, TIEM Assembly Sites



Process Difference Summary:

	(Current Site)		(New Site)
	ZVEI ID		
Assembly site	SEM-PA-18	CDAT	TIEMA
Lead frame finish or plating technique	SEM-PA-05	NiPdAu	Sn

Assembly Characterization Data – 2DPY package:

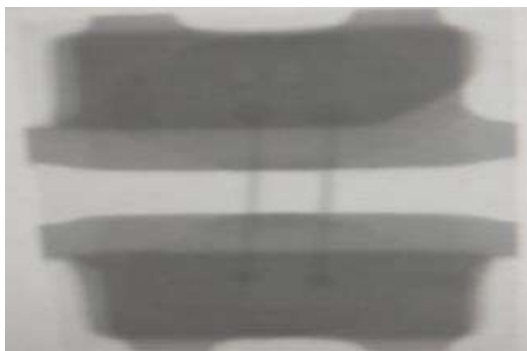
Purpose	Assembly MQ
Device	ESD761DPYR
Package type/Pin Count	DPY/2
Results	PASS
Notes	

Assembly Data	Sample size	Units of measure	USL	LSL	Manufacturability Data			
					Average	Std Dev	CpK	Remarks
Ball Shear	76	gmF	0	9.5	27.66	2.05	>1.67	PASS
Die Shear	30	gmF	2.5	0.065	65.37	12.12	>1.67	PASS
Wire Pull	76	gmF	0	2.5	8.40	0.68	>1.67	PASS

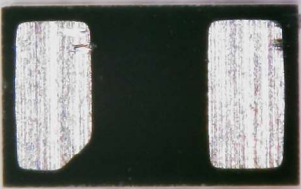
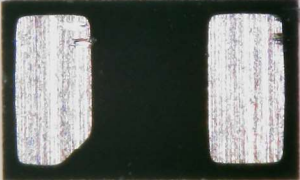
Cpk values > 2.0 are 6sigma limits with DPPM rates of less than 0.00198 (parts per million) and exceed the TI Quality Guidelines.

Assembly Data: X-ray Data

Site: TIEM
Device: ESD761DPYR
Package Group: X1SON
Pin Count/Package: 2/DPY



Visual Comparison – 2DPY package

Material Name (Qual driver)	Current (Top)	Current (Bottom)	New (Top)	New (Bottom)	Difference Summary
ESD601DPYRQ1					Pin1 marking has changed not changed

Package Dimension Comparison

Device: ESD761DPYR

Package Dimension	Length (X)	Width (Y)	Height (Z)
Sample size	30	30	30
Units of Measure	mm	mm	mm
USL	1.1	0.7	0.45
LSL	0.9	0.5	0.30
Target	1.0	0.6	0.38
Average	0.964	0.564	0.395
Std Dev	0.007	0.006	0.008
CpK	>1.67	>1.67	>1.67
Remarks	Pass	Pass	Pass

The mechanical drawing illustrates the ESD761DPYR package dimensions. The top view shows a rectangular footprint with a length of 1.1 mm (USL) and 0.9 mm (LSL), and a width of 0.7 mm (USL) and 0.5 mm (LSL). A 'PIN 1 INDEX AREA' is indicated. The side view shows a height of 0.45 mm (USL) and 0.30 mm (LSL), with a 'SEATING PLANE' and a flatness tolerance of 0.08 mm. A detail view shows a pin with a diameter of 0.15 mm (USL) and 0.1 mm (LSL), a length of 0.55 mm (USL) and 0.45 mm (LSL), and a symmetry (SYMM) feature. A note indicates 'PIN 1 ID OPTIONAL (45° X 0.1)'.

Conclusion

- The Assembly site change TIEM has been qualified.
- Texas Instruments is pleased to release the TIEM Assembly site facility as a source for the devices listed in “Product Affected” section of the PCN notice.
- For further information or questions, please contact your PCN representative.

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